



Material Content Data Sheet



Sales Product Name				BGSX 28MA18 E6327		Issued		3. July 2019	
MA#				MA004221200					
Package				PG-ATSLP-18-4		Weight*		6.41 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.223	3.49	3.49	34859	34859	
bumps	noble metal	silver	7440-22-4	0.000	0.00		25		
	non noble metal	tin	7440-31-5	0.009	0.14		1388		
encapsulation	non noble metal	copper	7440-50-8	0.025	0.39	0.53	3896	5309	
	organic material	carbon black	1333-86-4	0.023	0.36		3642		
	plastics	epoxy resin	-	0.677	10.56		105607		
leadfinish	inorganic material	silicondioxide	60676-86-0	3.967	61.91	72.83	619075	728324	
	noble metal	gold	7440-57-5	0.059	0.92		9211		
substrate	non noble metal	nickel	7440-02-0	0.067	1.05	1.97	10505	19716	
	organic material	carbon black	1333-86-4	0.002	0.03		310		
	plastics	epoxy resin	-	0.078	1.21		12102		
	non noble metal	copper	7440-50-8	0.505	7.88		78800		
ubm	inorganic material	silicondioxide	60676-86-0	0.583	9.10	18.22	91023	182235	
	non noble metal	tungsten	7440-33-7	0.000	0.00		49		
	non noble metal	titanium	7440-32-6	0.001	0.01		94		
solder resists	non noble metal	copper	7440-50-8	0.002	0.03	0.04	266	409	
	inorganic material	silicondioxide	60676-86-0	0.040	0.62		6194		
	inorganic material	bariumsulfate	7727-43-7	0.040	0.63		6267		
	plastics	acrylic resin	-	0.107	1.67	2.92	16687	29148	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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